AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF THE CLAIMS:

1-8. (Canceled).

9. (Currently Amended) A press-fit diode, comprising:

a diode chip;

a base contact for pressing the press-fit diode into a substrate, wherein the base contact is attached to the diode chip and forms a first terminal of the press-fit diode; and

a nickel layered wire contact ~~attached~~ soldered to the diode chip ~~at a temperature greater than a silver-solder alloy melting point~~ to form a second terminal of the press-fit diode, wherein only a section of the nickel layered wire contact, which is not soldered to the diode chip, ~~remaining unexposed to solder during manufacturing of the press-fit diode~~ is plated with silver.

10. (Canceled).

11. (Currently Amended) The press-fit diode as recited in claim [[10]] 9, wherein the base contact is not provided with a silver layer.

12. (Canceled).

13. (Currently Amended) A method for manufacturing a press-fit diode, comprising:

providing a diode chip;

providing a base contact configured for pressing the press-fit diode into a substrate, wherein the base contact forms a first terminal of the press-fit diode;

~~providing~~ soldering a nickel layered wire contact having a wire head and a wire shaft to the diode chip to form ~~which forms~~ a second terminal of the press-fit diode,

immersing the wire shaft of the wire contact in an electroplating vat to silver plate only a section of the nickel layered wire shaft, which is not soldered to the diode chip; ~~remaining unexposed to solder during manufacturing of the press-fit diode;~~ and

fixedly connecting the wire head and base contact to the diode chip. ~~at a wire head temperature exceeding a melting point of a silver-solder alloy.~~

14. (Canceled).

15. (Previously Presented) The method as recited in claim 13, wherein the base contact is not provided with a silver layer.

16. (Canceled).

17. (Previously Presented) The method as recited in claim 13, wherein the wire contact is made of copper, and wherein the wire contact has the nickel layer on which the silver layer is applied.

18. (Canceled).

19. (Canceled).

20. (Previously Presented) The press-fit diode as recited in claim 9, wherein a region for attaching the diode chip is recessed.

21. (Currently Amended) The press-fit diode as recited in claim 9, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, and wherein the wire shaft is electroplated ~~immersed in an electroplating vat~~.

22. (Previously Presented) The press-fit diode as recited in claim 9, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip.

23. (Currently Amended) The press-fit diode as recited in claim 9, wherein the press-fit diode is electroplated ~~in bulk in a drum process~~.

24. (Previously Presented) The method as recited in claim 13, further comprising:

applying the silver layer before the press-fit diode is assembled.

25. (Previously Presented) The method as recited in claim 13, wherein a region for attaching the diode chip is recessed.

26. (Previously Presented) The method as recited in claim 13, further comprising:

inserting the wire contact in a rack with a wire shaft pointing downward; and

immersing the wire shaft in an electroplating vat.

27. (Previously Presented) The method as recited in claim 13, further comprising:

sheathing a central section of the press-fit diode to protect the diode chip.

28. (Previously Presented) The method as recited in claim 13, wherein the press-fit diode is electroplated in bulk in a drum process.

29. (Currently Amended) The press-fit diode as recited in claim 9, ~~wherein the silver layer is applied before the press-fit diode is assembled,~~ wherein a region for attaching the diode chip is recessed, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, wherein the wire shaft is electroplated ~~immersed in an electroplating vat~~, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip, and wherein the press-fit diode is electroplated ~~in bulk in a drum process~~.

30. (Previously Presented) The method as recited in claim 13, further comprising:

inserting the wire contact in a rack with a wire shaft pointing downward;

immersing the wire shaft in an electroplating vat. wherein a region for attaching the diode chip is recessed; and

sheathing a central section of the press-fit diode to protect the diode chip;

wherein the press-fit diode is electroplated in bulk in a drum process.